

L Number	Hits	Search Text	DB	Time stamp
1	235	(((silylation and heat\$3) and pin ) or (((118/715,724,725,726).CCLS.) and (heat or heated or heating) and (lift adj pin) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas)) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas) ) or (((118/715,724,725,726).CCLS.) and (gas adj ring) ) or ((heat or heating or heated) and (lift adj pin) and (gas near ring) ) or (((heat or heating or heated) and (lift adj pin) and (ring) ) and (substrate or wafer) )) and @pd>=20021022) or (((preheat or preheated or preheating) or (pre adj (heat or heating or heated))) and (lift adj pin) and (ring) ) and (substrate or wafer) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:31
2	84	(((silylation and heat\$3) and pin ) or (((118/715,724,725,726).CCLS.) and (heat or heated or heating) and (lift adj pin) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas)) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas) ) or (((118/715,724,725,726).CCLS.) and (gas adj ring) ) or ((heat or heating or heated) and (lift adj pin) and (gas near ring) ) or (((heat or heating or heated) and (lift adj pin) and (ring) ) and (substrate or wafer) )) and @pd>=20021022) or (((preheat or preheated or preheating) or (pre adj (heat or heating or heated))) and (lift adj pin) and (ring) ) and (substrate or wafer) )) and @pd>=20030321	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:35
-	4323	silylation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:41
-	2976	silylation and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:42
-	49	(silylation and heat\$3) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	9099	((118/715,724,725,726).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/22 17:54
-	156	(((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	20	(((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:11

-	126	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 10:28
-	126	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 11:57
-	20	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	156	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	27	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) ) not (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring ) (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)) and bubbler ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 08:12
-	4	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((purge or inert) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 10:45
-	0	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:06
-	32	((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	62	((118/715,724,725,726).CCLS.) and (gas adj ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	54	heat\$3 and (lift adj pin) and (gas near ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:08

-	44	(heat\$3 and (lift adj pin) and (gas near ring) ) not (((118/715,724,725,726).CCLS.) and (gas adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:05
-	617	heat\$3 and (lift adj pin) and (ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:17
-	494	(heat\$3 and (lift adj pin) and (ring) ) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:08
-	327	((heat\$3 and (lift adj pin) and (ring) ) and (substrate or wafer)) not (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) and ring ) (heat\$3 and (lift adj pin) and (gas near ring) ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 12:19
-	219	lund-j\$.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 15:29
-	207	lund-j\$.xp.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/23 15:29
-	28	("3830194"   "4125391"   "4493977"   "4503807"   "4533820"   "4817558"   "4828224"   "4836138"   "4854263"   "4920918"   "4958061"   "4993358"   "5000113"   "5085887"   "5113929"   "5148714"   "5156820"   "5179677"   "5198034"   "5215588"   "5269847"   "5305417"   "5414244"   "5444815"   "5445675"   "5446825"   "5487127"   "5970213").PN.	USPAT	2002/10/23 15:43
-	57	4817558.URPN.	USPAT	2002/10/23 15:44
-	144	(lund-j\$.xa. or lund-j\$.xp.) and (electrode or showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2002/10/30 13:52
-	60	(silylation and heat\$3) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:03
-	178	((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:05

-	0	((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:06
-	34	((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	67	((118/715,724,725,726).CCLS.) and (gas adj ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:07
-	74	heat\$3 and (lift adj pin) and (gas near ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:09
-	584	(heat\$3 and (lift adj pin) and (ring) ) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 19:42
-	112	(((silylation and heat\$3) and pin ) or (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas)) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas) ) or (((118/715,724,725,726).CCLS.) and (gas adj ring) ) or (heat\$3 and (lift adj pin) and (gas near ring) ) or ((heat\$3 and (lift adj pin) and (ring) ) and (substrate or wafer) )) and @pd>=20021022	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:18
-	49	((preheat\$3 or (pre adj heat\$3)) and (lift adj pin) and (ring) ) and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:19
-	151	(((silylation and heat\$3) and pin ) or (((118/715,724,725,726).CCLS.) and heat\$3 and (lift adj pin) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with ((sweep) adj gas)) ) or (((118/715,724,725,726).CCLS.) and ((lift adj pin) with gas) ) or (((118/715,724,725,726).CCLS.) and (gas adj ring) ) or (heat\$3 and (lift adj pin) and (gas near ring) ) or ((heat\$3 and (lift adj pin) and (ring) ) and (substrate or wafer) )) and @pd>=20021022 or (((preheat\$3 or (pre adj heat\$3)) and (lift adj pin) and (ring) ) and (substrate or wafer) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/07/17 18:25
-	3	("6402401").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:44

-	0	((("6402401").PN.) and pin and silation and (preheat\$3 or (pre adj heat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:46
-	0	((("6402401").PN.) and pin and (preheat\$3 or (pre adj heat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:47
-	1	((("6402401").PN.) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2003/03/21 20:47